ABSTRACT

A method of measuring the stress migration of vias, and a the structure, the method comprising the following steps. A metal line having a middle and opposing first and second ends is formed. First and second opposing pads electrically connected to the respective opposing first and second ends of the metal line through respective first and second step-width line structures are formed. A third pad connected to the metal line proximate its first end by a first via through a first metal structure is formed. A fourth pad connected to the metal line proximate its second end by a second via through a second metal structure is formed. The first and second vias are equidistant from the respective first and second ends of the metal line. The stress migration of the first via is determined by measuring the: sheet resistance between the first pad and the third pad; and/or the stress migration of the second via is determined by measuring the sheet resistance between the fourth pad and the second pad.